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Understanding **Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	7612
Number of Logic Elements/Cells	181165
Total RAM Bits	10177536
Number of I/O	372
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2agx190ef29c5

Table 1–6. Recommended Operating Conditions for Arria II GZ Devices (*Note 6*) (Part 2 of 2)

Symbol	Description	Condition	Minimum	Typical	Maximum	Unit
V_{CCL_GXBLn} <i>(3)</i>	Transceiver clock power (left side)	—	1.05	1.1	1.15	V
V_{CCL_GXBRn} <i>(3)</i>	Transceiver clock power (right side)	—	1.05	1.1	1.15	V
V_{CCH_GXBLn} <i>(3)</i>	Transmitter output buffer power (left side)	—				
V_{CCH_GXBRn} <i>(3)</i>	Transmitter output buffer power (right side)	—	1.33/1.425	1.4/1.5 <i>(5)</i>	1.575	V
T_J	Operating junction temperature	Commercial	0	—	85	°C
		Industrial	-40	—	100	°C
t_{RAMP}	Power supply ramp time	Normal POR (PORSEL=0)	0.05	—	100	ms
		Fast POR (PORSEL=1)	0.05	—	4	ms

Notes to Table 1–6:

- (1) Altera recommends a 3.0-V nominal battery voltage when connecting V_{CCBAT} to a battery for volatile key backup. If you do not use the volatile security key, you may connect the V_{CCBAT} to either GND or a 3.0-V power supply.
- (2) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (3) $n = 0, 1,$ or $2.$
- (4) $V_{CCA_L/R}$ must be connected to a 3.0-V supply if the clock multiplier unit (CMU) phase-locked loop (PLL), receiver clock data recovery (CDR), or both, are configured at a base data rate > 4.25 Gbps. For data rates up to 4.25 Gbps, you can connect $V_{CCA_L/R}$ to either 3.0 V or 2.5 V.
- (5) $V_{CCH_GXBL/R}$ must be connected to a 1.4-V supply if the transmitter channel data rate is > 6.5 Gbps. For data rates up to 6.5 Gbps, you can connect $V_{CCH_GXBL/R}$ to either 1.4 V or 1.5 V.
- (6) Transceiver power supplies do not have power-on-reset (POR) circuitry. After initial power-up, violating the transceiver power supply operating conditions could lead to unpredictable link behavior.

DC Characteristics

This section lists the supply current, I/O pin leakage current, on-chip termination (OCT) accuracy and variation, input pin capacitance, internal weak pull-up and pull-down resistance, hot socketing, and Schmitt trigger input specifications.

Supply Current

Standby current is the current the device draws after the device is configured with no inputs or outputs toggling and no activity in the device. Because these currents vary largely with the resources used, use the Microsoft Excel-based Early Power Estimator (EPE) to get supply current estimates for your design.

 For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter.

I/O Pin Leakage Current

Table 1-7 lists the Arria II GX I/O pin leakage current specifications.

Table 1-7. I/O Pin Leakage Current for Arria II GX Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0 \text{ V to } V_{CCIO MAX}$	-10	—	10	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO MAX}$	-10	—	10	μA

Table 1-8 lists the Arria II GZ I/O pin leakage current specifications.

Table 1-8. I/O Pin Leakage Current for Arria II GZ Devices

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0 \text{ V to } V_{CCIO MAX}$	-20	—	20	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO MAX}$	-20	—	20	μA

Bus Hold

Bus hold retains the last valid logic state after the source driving it either enters the high impedance state or is removed. Each I/O pin has an option to enable bus hold in user mode. Bus hold is always disabled in configuration mode.

Table 1-9 lists bus hold specifications for Arria II GX devices.

Table 1-9. Bus Hold Parameters for Arria II GX Devices (Note 1)

Parameter	Symbol	Cond.	$V_{CCIO} (\text{V})$												Unit	
			1.2		1.5		1.8		2.5		3.0		3.3			
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Bus-hold low, sustaining current	I_{SUSL}	$V_{IN} > V_{IL} (\text{max.})$	8	—	12	—	30	—	50	—	70	—	70	—	μA	
Bus-hold high, sustaining current	I_{SUSH}	$V_{IN} < V_{IL} (\text{min.})$	-8	—	-12	—	-30	—	-50	—	-70	—	-70	—	μA	
Bus-hold low, overdrive current	I_{ODL}	$0 \text{ V} < V_{IN} < V_{CCIO}$	—	125	—	175	—	200	—	300	—	500	—	500	μA	
Bus-hold high, overdrive current	I_{ODH}	$0 \text{ V} < V_{IN} < V_{CCIO}$	—	-125	—	-175	—	-200	—	-300	—	-500	—	-500	μA	
Bus-hold trip point	V_{TRIP}	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V	

Note to Table 1-9:

- (1) The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

The calibration accuracy for calibrated series and parallel OCTs are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Table 1–13 lists the Arria II GZ OCT without calibration resistance tolerance to PVT changes.

Table 1–13. OCT Without Calibration Resistance Tolerance Specifications for Arria II GZ Devices

Symbol	Description	Conditions (V)	Resistance Tolerance		Unit
			C3,I3	C4,I4	
25- Ω R_S 3.0 and 2.5	25- Ω internal series OCT without calibration	$V_{CCIO} = 3.0, 2.5$	± 40	± 40	%
25- Ω R_S 1.8 and 1.5	25- Ω internal series OCT without calibration	$V_{CCIO} = 1.8, 1.5$	± 40	± 40	%
25- Ω R_S 1.2	25- Ω internal series OCT without calibration	$V_{CCIO} = 1.2$	± 50	± 50	%
50- Ω R_S 3.0 and 2.5	50- Ω internal series OCT without calibration	$V_{CCIO} = 3.0, 2.5$	± 40	± 40	%
50- Ω R_S 1.8 and 1.5	50- Ω internal series OCT without calibration	$V_{CCIO} = 1.8, 1.5$	± 40	± 40	%
50- Ω R_S 1.2	50- Ω internal series OCT without calibration	$V_{CCIO} = 1.2$	± 50	± 50	%
100- Ω R_D 2.5	100- Ω internal differential OCT	$V_{CCIO} = 2.5$	± 25	± 25	%

OCT calibration is automatically performed at power up for OCT-enabled I/Os. When voltage and temperature conditions change after calibration, the resistance may change. Use Equation 1–1 and Table 1–14 to determine the OCT variation when voltage and temperature vary after power-up calibration for Arria II GX and GZ devices.

Equation 1–1. OCT Variation (*Note 1*)

$$R_{OCT} = R_{SCAL} \left(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \right)$$

Notes to Equation 1–1:

- (1) R_{OCT} value calculated from Equation 1–1 shows the range of OCT resistance with the variation of temperature and V_{CCIO} .

I/O Standard Specifications

Table 1–22 through **Table 1–35** list input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by the Arria II device family. They also show the Arria II device family I/O standard specifications. V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.



For an explanation of terms used in **Table 1–22** through **Table 1–35**, refer to “[Glossary](#)” on page [1–74](#).

Table 1–22 lists the single-ended I/O standards for Arria II GX devices.

Table 1–22. Single-Ended I/O Standards for Arria II GX Devices

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
3.3 V LVTTL	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.45	2.4	4	-4
3.3 V LVCMOS	3.135	3.3	3.465	-0.3	0.8	1.7	3.6	0.2	$V_{CCIO} - 0.2$	2	-2
3.0 V LVTTL	2.85	3	3.15	-0.3	0.8	1.7	$V_{CCIO} + 0.3$	0.45	2.4	4	-4
3.0 V LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	$V_{CCIO} + 0.3$	0.2	$V_{CCIO} - 0.2$	0.1	-0.1
2.5 V LVCMOS	2.375	2.5	2.625	-0.3	0.7	1.7	$V_{CCIO} + 0.3$	0.4	2	1	-1
1.8 V LVCMOS	1.71	1.8	1.89	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	0.45	$V_{CCIO} - 0.45$	2	-2
1.5 V LVCMOS	1.425	1.5	1.575	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
1.2 V LVCMOS	1.14	1.2	1.26	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2
3.0-V PCI	2.85	3	3.15	—	$0.3 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5
3.0-V PCI-X	2.85	3	3.15	—	$0.35 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	1.5	-0.5

Table 1–23 lists the single-ended I/O standards for Arria II GZ devices.

Table 1–23. Single-Ended I/O Standards for Arria II GZ Devices (Part 1 of 2)

I/O Standard	V_{CCIO} (V)			V_{IL} (V)		V_{IH} (V)		V_{OL} (V)	V_{OH} (V)	I_{OL} (mA)	I_{OH} (mA)
	Min	Typ	Max	Min	Max	Min	Max	Max	Min		
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	$V_{CCIO} - 0.2$	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	0.45	$V_{CCIO} - 0.45$	2	-2
1.5 V	1.425	1.5	1.575	-0.3	$0.35 \times V_{CCIO}$	$0.65 \times V_{CCIO}$	$V_{CCIO} + 0.3$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	2	-2

Table 1–26 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GX devices.

Table 1–26. Single-Ended SSTL and HSTL I/O Standard Signal Specifications for Arria II GX Devices

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL} (mA)	I _{OH} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	V _{REF} - 0.18	V _{REF} + 0.18	V _{CCIO} + 0.3	V _{REF} - 0.35	V _{REF} + 0.35	V _{TT} - 0.57	V _{TT} + 0.57	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.18	V _{REF} + 0.18	V _{CCIO} + 0.3	V _{REF} - 0.35	V _{REF} + 0.35	V _{TT} - 0.76	V _{TT} + 0.76	16.4	-16.4
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.475	V _{TT} + 0.475	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4
SSTL-15 Class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	8	-8
SSTL-15 Class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	16	-16
HSTL-18 Class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	8	-8
HSTL-18 Class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	16	-16
HSTL-15 Class I	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	8	-8
HSTL-15 Class II	-0.3	V _{REF} - 0.1	V _{REF} + 0.1	V _{CCIO} + 0.3	V _{REF} - 0.2	V _{REF} + 0.2	0.4	V _{CCIO} - 0.4	16	-16
HSTL-12 Class I	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} - 0.15	V _{REF} + 0.15	0.25 × V _{CCIO}	0.75 × V _{CCIO}	8	-8
HSTL-12 Class II	-0.15	V _{REF} - 0.08	V _{REF} + 0.08	V _{CCIO} + 0.15	V _{REF} - 0.15	V _{REF} + 0.15	0.25 × V _{CCIO}	0.75 × V _{CCIO}	14	-14

Table 1–27 lists the single-ended SSTL and HSTL I/O standard signal specifications for Arria II GZ devices.

Table 1–27. Single-Ended SSTL and HSTL I/O Standards Signal Specifications for Arria II GZ Devices (Part 1 of 2)

I/O Standard	V _{IL(DC)} (V)		V _{IH(DC)} (V)		V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I _{OL} (mA)	I _{OH} (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.57	V _{TT} + 0.57	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} - 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} - 0.31	V _{REF} + 0.31	V _{TT} - 0.76	V _{TT} + 0.76	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	V _{TT} - 0.475	V _{TT} + 0.475	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} - 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} - 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4
SSTL-15 Class I	—	V _{REF} - 0.1	V _{REF} + 0.1	—	V _{REF} - 0.175	V _{REF} + 0.175	0.2 × V _{CCIO}	0.8 × V _{CCIO}	8	-8

Table 1–35. Transceiver Specifications for Arria II GZ Devices (Part 2 of 5)

Symbol/ Description	Conditions	–C3 and –I3 (1)			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Transceiver Clocks								
Calibration block clock frequency (cal_blk_clk)	—	10	—	125	10	—	125	MHz
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	MHz
reconfig_clk clock frequency	Dynamic reconfiguration clock frequency	2.5/37.5 (4)	—	50	2.5/37.5 (4)	—	50	MHz
Delta time between reconfig_clks (5)	—	—	—	2	—	—	2	ms
Transceiver block minimum power-down (gxb_powerdown) pulse width	—	1	—	—	1	—	—	μs
Receiver								
Supported I/O Standards	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS							
Data rate (16)	—	600	—	6375	600	—	3750	Mbps
Absolute V _{MAX} for a receiver pin (6)	—	—	—	1.6	—	—	1.6	V
Operational V _{MAX} for a receiver pin	—	—	—	1.5	—	—	1.5	V
Absolute V _{MIN} for a receiver pin	—	-0.4	—	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration	V _{ICM} = 0.82 V setting	—	—	2.7	—	—	2.7	V
	V _{ICM} = 1.1 V setting (7)	—	—	1.6	—	—	1.6	V
Minimum differential eye opening at receiver serial input pins (8)	Data Rate = 600 Mbps to 5 Gbps Equalization = 0 DC gain = 0 dB	100	—	—	165	—	—	mV
	Data Rate > 5 Gbps Equalization = 0 DC gain = 0 dB	165	—	—	165	—	—	mV
V _{ICM}	V _{ICM} = 0.82 V setting	820 ± 10%			820 ± 10%			mV
	V _{ICM} = 1.1 V setting (7)	1100 ± 10%			1100 ± 10%			mV

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (*Note 1*) (Part 6 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 20 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 1			> 1			> 1			> 1			UI
	Jitter frequency = 100 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			> 0.2			> 0.2			UI
	Jitter frequency = 148.5 MHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			> 0.2			> 0.2			UI

SATA Transmit Jitter Generation (10)

Total jitter at 1.5 Gbps (G1)	Compliance pattern	—	—	0.55	—	—	0.55	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 1.5 Gbps (G1)	Compliance pattern	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Total jitter at 3.0 Gbps (G2)	Compliance pattern	—	—	0.55	—	—	0.55	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 3.0 Gbps (G2)	Compliance pattern	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Total jitter at 6.0 Gbps (G3)	Compliance pattern	—	—	0.52	—	—	—	—	—	—	—	—	—	UI
Random jitter at 6.0 Gbps (G3)	Compliance pattern	—	—	0.18	—	—	—	—	—	—	—	—	—	UI

SATA Receiver Jitter Tolerance (10)

Total jitter tolerance at 1.5 Gbps (G1)	Compliance pattern	> 0.65			> 0.65			> 0.65			> 0.65			UI
Deterministic jitter tolerance at 1.5 Gbps (G1)	Compliance pattern	> 0.35			> 0.35			> 0.35			> 0.35			UI
SSC modulation frequency at 1.5 Gbps (G1)	Compliance pattern	33			33			33			33			kHz

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (*Note 1*) (Part 8 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max										
CPRI Transmit Jitter Generation (11)														
Total jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.279	—	—	0.279	—	—	0.279	—	—	0.279	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Deterministic jitter	E.6.HV, E.12.HV Pattern = CJPAT	—	—	0.14	—	—	0.14	—	—	0.14	—	—	0.14	UI
	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI
CPRI Receiver Jitter Tolerance (11)														
Total jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.66			> 0.66			> 0.66			> 0.66			UI
Deterministic jitter tolerance	E.6.HV, E.12.HV Pattern = CJPAT	> 0.4			> 0.4			> 0.4			> 0.4			UI
Total jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.65			> 0.65			> 0.65			> 0.65			UI
	E.60.LV Pattern = PRBS31	> 0.6			—			—			—			UI
Deterministic jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.37			> 0.37			> 0.37			> 0.37			UI
	E.60.LV Pattern = PRBS31	> 0.45			—			—			—			UI
Combined deterministic and random jitter tolerance	E.6.LV, E.12.LV, E.24.LV, E.30.LV Pattern = CJTPAT	> 0.55			> 0.55			> 0.55			> 0.55			UI
OBSAI Transmit Jitter Generation (12)														
Total jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern = CJPAT	—	—	0.35	—	—	0.35	—	—	0.35	—	—	0.35	UI
Deterministic jitter at 768 Mbps, 1536 Mbps, and 3072 Mbps	REFCLK = 153.6 MHz Pattern = CJPAT	—	—	0.17	—	—	0.17	—	—	0.17	—	—	0.17	UI

Table 1–40. Transceiver Block Jitter Specifications for Arria II GX Devices (*Note 1*) (Part 10 of 10)

Symbol/ Description	Conditions	I3			C4			C5, I5			C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance at 3072 Mbps	Jitter frequency = 21.8 KHz Pattern = CJPAT	> 8.5			> 8.5			> 8.5			> 8.5			UI
	Jitter frequency = 1843.2 KHz to 20 MHz Pattern = CJPAT	> 0.1			> 0.1			> 0.1			> 0.1			UI

Notes to Table 1–40:

- (1) Dedicated `refclk` pins are used to drive the input reference clocks. The jitter numbers are valid for the stated conditions only.
- (2) The jitter numbers for SONET/SDH are compliant to the GR-253-CORE Issue 3 Specification.
- (3) The jitter numbers for XAUI are compliant to the IEEE802.3ae-2002 Specification.
- (4) The jitter numbers for PCIe are compliant to the PCIe Base Specification 2.0.
- (5) The jitter numbers for SRIO are compliant to the RapidIO Specification 1.3.
- (6) The jitter numbers for GIGE are compliant to the IEEE802.3-2002 Specification.
- (7) The jitter numbers for HiGig are compliant to the IEEE802.3ae-2002 Specification.
- (8) The HD-SDI and 3G-SDI jitter numbers are compliant to the SMPTE292M and SMPTE424M Specifications.
- (9) Arria II PCIe receivers are compliant to this specification provided the `VTX_CM-DC-ACTIVEIDLE-DELTA` of the upstream transmitter is less than 50 mV.
- (10) The jitter numbers for Serial Advanced Technology Attachment (SATA) are compliant to the Serial ATA Revision 3.0 Specification.
- (11) The jitter numbers for Common Public Radio Interface (CPRI) are compliant to the CPRI Specification V3.0.
- (12) The jitter numbers for Open Base Station Architecture Initiative (OBSAI) are compliant to the OBSAI RP3 Specification V4.1.

Table 1–41 lists the transceiver jitter specifications for all supported protocols for Arria II GZ devices.

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (*Note 1*), (*2*) (Part 1 of 7)

Symbol/ Description	Conditions	-C3 and -I3			-C4 and -I4			Unit
		Min	Typ	Max	Min	Typ	Max	
SONET/SDH Transmit Jitter Generation (<i>3</i>)								
Peak-to-peak jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	UI
RMS jitter at 622.08 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	UI
Peak-to-peak jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.1	—	—	0.1	UI
RMS jitter at 2488.32 Mbps	Pattern = PRBS15	—	—	0.01	—	—	0.01	UI
SONET/SDH Receiver Jitter Tolerance (<i>3</i>)								
Jitter tolerance at 622.08 Mbps	Jitter frequency = 0.03 KHz Pattern = PRBS15	> 15			> 15			UI
	Jitter frequency = 25 KHz Pattern = PRBS15	> 1.5			> 1.5			UI
	Jitter frequency = 250 KHz Pattern = PRBS15	> 0.15			> 0.15			UI

Table 1–41. Transceiver Block Jitter Specifications for Arria II GZ Devices (Note 1), (2) (Part 5 of 7)

Symbol/ Description	Conditions	–C3 and –I3			–C4 and –I4			Unit
		Min	Typ	Max	Min	Typ	Max	
Sinusoidal jitter tolerance (peak-to-peak)	Jitter Frequency = 38.2 KHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10^{-12}	> 0.5			—	—	—	UI
	Jitter Frequency = 3.82 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10^{-12}	> 0.05			—	—	—	UI
	Jitter Frequency = 20 MHz Data rate = 6.375 Gbps Pattern = PRBS31 BER = 10^{-12}	> 0.05			—	—	—	UI
SDI Transmitter Jitter Generation (12)								
Alignment jitter (peak-to-peak)	Data rate = 1.485 Gbps (HD) Pattern = color bar Low-frequency roll-off = 100 KHz	0.2	—	—	0.2	—	—	UI
	Data rate = 2.97 Gbps (3G) Pattern = color bar Low-frequency roll-off = 100 KHz	0.3	—	—	0.3	—	—	UI
SDI Receiver Jitter Tolerance (12)								
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 15 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 2			> 2			UI
	Jitter frequency = 100 KHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
	Jitter frequency = 148.5 MHz Data rate = 2.97 Gbps (3G) Pattern = single line scramble color bar	> 0.3			> 0.3			UI
Sinusoidal jitter tolerance (peak-to-peak)	Jitter frequency = 20 KHz Data rate = 1.485 Gbps (HD) pattern = 75% color bar	> 1			> 1			UI
	Jitter frequency = 100 KHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
	Jitter frequency = 148.5 MHz Data rate = 1.485 Gbps (HD) Pattern = 75% color bar	> 0.2			> 0.2			UI
SAS Transmit Jitter Generation (13)								
Total jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI
Deterministic jitter at 1.5 Gbps (G1)	Pattern = CJPAT	—	—	0.35	—	—	0.35	UI
Total jitter at 3.0 Gbps (G2)	Pattern = CJPAT	—	—	0.55	—	—	0.55	UI

DSP Block Specifications

Table 1–46 lists the DSP block performance specifications for Arria II GX devices.

Table 1–46. DSP Block Performance Specifications for Arria II GX Devices (Note 1)

Mode	Resources Used	Performance				Unit
	Number of Multipliers	C4	I3	C5,I5	C6	
9 × 9-bit multiplier	1	380	310	300	250	MHz
12 × 12-bit multiplier	1	380	310	300	250	MHz
18 × 18-bit multiplier	1	380	310	300	250	MHz
36 × 36-bit multiplier	1	350	270	270	220	MHz
18 × 36-bit high-precision multiplier adder mode	1	350	270	270	220	MHz
18 × 18-bit multiply accumulator	4	380	310	300	250	MHz
18 × 18-bit multiply adder	4	380	310	300	250	MHz
18 × 18-bit multiply adder-signed full precision	2	380	310	300	250	MHz
18 × 18-bit multiply adder with loopback (2)	2	275	220	220	180	MHz
36-bit shift (32-bit data)	1	350	270	270	220	MHz
Double mode	1	350	270	270	220	MHz

Notes to Table 1–46:

- (1) Maximum is for a fully-pipelined block with **Round** and **Saturation** disabled.
- (2) Maximum is for loopback input registers disabled, **Round** and **Saturation** disabled, pipeline and output registers enabled.

Table 1–47 lists the DSP block performance specifications for Arria II GZ devices.

Table 1–47. DSP Block Performance Specifications for Arria II GZ Devices (Note 1) (Part 1 of 2)

Mode	Resources Used	Performance		Unit
	Number of Multipliers	-3	-4	
9 × 9-bit multiplier	1	460	400	MHz
12 × 12-bit multiplier	1	500	440	MHz
18 × 18-bit multiplier	1	550	480	MHz
36 × 36-bit multiplier	1	440	380	MHz
18 × 18-bit multiply accumulator	4	440	380	MHz
18 × 18-bit multiply adder	4	470	410	MHz
18 × 18-bit multiply adder-signed full precision	2	450	390	MHz
18 × 18-bit multiply adder with loopback (2)	2	350	310	MHz
36-bit shift (32-bit data)	1	440	380	MHz

Table 1–47. DSP Block Performance Specifications for Arria II GZ Devices (*Note 1*) (Part 2 of 2)

Mode	Resources Used	Performance			Unit
	Number of Multipliers	-3	-4		
Double mode	1	440	380	MHz	

Notes to Table 1–47:

- (1) Maximum is for fully pipelined block with **Round** and **Saturation** disabled.
- (2) Maximum for loopback input registers disabled, **Round** and **Saturation** disabled, and pipeline and output registers enabled.

Embedded Memory Block Specifications

Table 1–48 lists the embedded memory block specifications for Arria II GX devices.

Table 1–48. Embedded Memory Block Performance Specifications for Arria II GX Devices

Memory	Mode	Resources Used		Performance				Unit
		ALUTs	Embedded Memory	I3	C4	C5,I5	C6	
Memory Logic Array Block (MLAB)	Single port 64 × 10	0	1	450	500	450	378	MHz
	Simple dual-port 32 × 20 single clock	0	1	270	500	450	378	MHz
	Simple dual-port 64 × 10 single clock	0	1	428	500	450	378	MHz
M9K Block	Single-port 256 × 36	0	1	360	400	360	310	MHz
	Single-port 256 × 36, with the read-during-write option set to Old Data	0	1	250	280	250	210	MHz
	Simple dual-port 256 × 36 single CLK	0	1	360	400	360	310	MHz
	Single-port 256 × 36 single CLK, with the read-during-write option set to Old Data	0	1	250	280	250	210	MHz
	True dual port 512 × 18 single CLK	0	1	360	400	360	310	MHz
	True dual-port 512 × 18 single CLK, with the read-during-write option set to Old Data	0	1	250	280	250	210	MHz
	Min Pulse Width (clock high time)	—	—	900	850	950	1130	ps
	Min Pulse Width (clock low time)	—	—	730	690	770	920	ps

Table 1–53. High-Speed I/O Specifications for Arria II GX Devices (Part 3 of 4)

Symbol	Conditions	I3		C4		C5,I5		C6		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{TX_JITTER} (4)	True LVDS with dedicated SERDES (data rate 600–1,250 Mbps)	—	175	—	175	—	225	—	300	ps
	True LVDS with dedicated SERDES (data rate < 600 Mbps)	—	0.105	—	0.105	—	0.135	—	0.18	UI
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate 600 – 945 Mbps)	—	260	—	260	—	300	—	350	ps
	True LVDS and emulated LVDS_E_3R with logic elements as SERDES (data rate < 600 Mbps)	—	0.16	—	0.16	—	0.18	—	0.21	UI
t_{TX_DCD}	True LVDS and emulated LVDS_E_3R	45	55	45	55	45	55	45	55	%
t_{RISE} and t_{FALL}	True LVDS and emulated LVDS_E_3R	—	200	—	200	—	225	—	250	ps
TCCS	True LVDS (5)	—	150	—	150	—	175	—	200	ps
	Emulated LVDS_E_3R	—	200	—	200	—	250	—	300	ps
Receiver (6)										
True differential I/O standards - $f_{HSDRDPA}$ (data rate)	SERDES factor J = 3 to 10	150	1250	150	1250	150	1050	150	840	Mbps

Table 1–55. DPA Lock Time Specifications for Arria II Devices (Note 1), (2), (3)

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions (4)	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

Notes to Table 1–55:

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in the table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 1–5 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at a data rate less than 1.25 Gbps and all the Arria II GX devices.

Figure 1–5. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for All Arria II GX Devices and for Arria II GZ Devices at a Data Rate less than 1.25 Gbps

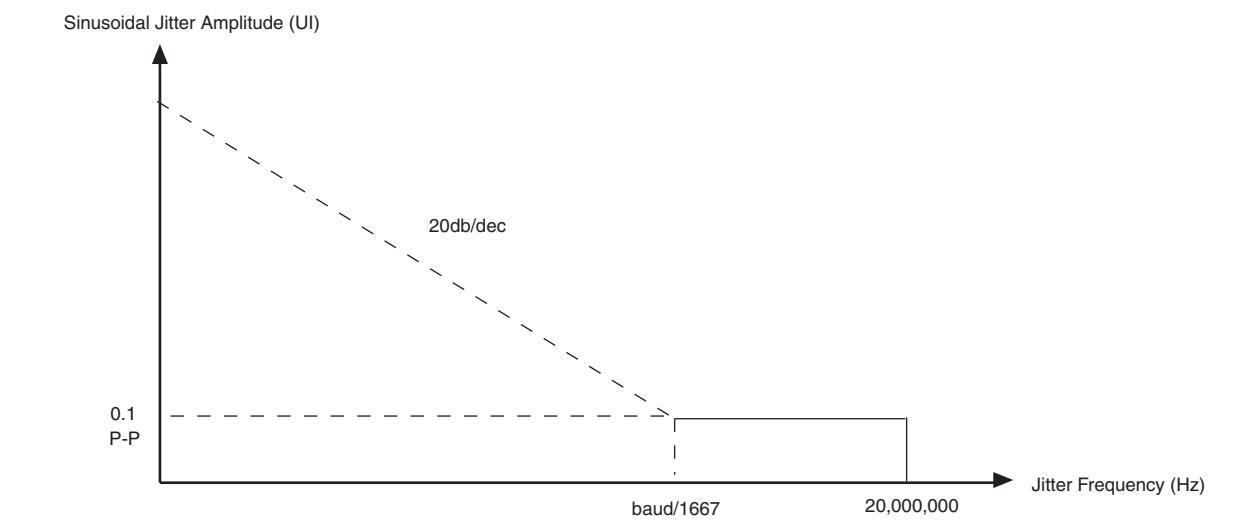


Figure 1–6 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at 1.25 Gbps data rate.

Figure 1–6. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for Arria II GZ Devices at a 1.25 Gbps Data Rate

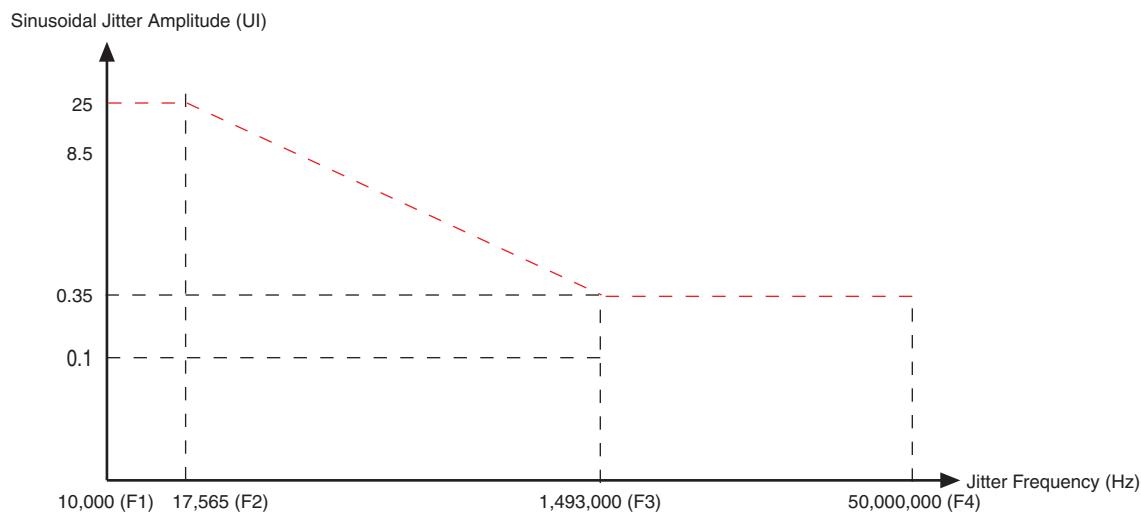


Table 1–56 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for Arria II GZ devices at 1.25 Gbps data rate.

Table 1–56. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for Arria II GZ Devices at 1.25 Gbps Data Rate

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

External Memory Interface Specifications

For the maximum clock rate supported for Arria II GX and GZ device family, refer to the [External Memory Interface Spec Estimator](#) page on the Altera website.

Table 1–57 lists the external memory interface specifications for Arria II GX devices.

Table 1–57. External Memory Interface Specifications for Arria II GX Devices (Part 1 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode (1)	Number of Delay Chains
	C4	I3, C5, I5	C6			
0	90-140	90-130	90-110	22.5	Low	16
1	110-180	110-170	110-150	30	Low	12
2	140-220	140-210	140-180	36	Low	10
3	170-270	170-260	170-220	45	Low	8
4	220-340	220-310	220-270	30	High	12

Table 1–57. External Memory Interface Specifications for Arria II GX Devices (Part 2 of 2)

Frequency Mode	Frequency Range (MHz)			Resolution (°)	DQS Delay Buffer Mode (1)	Number of Delay Chains
	C4	I3, C5, I5	C6			
5	270-410	270-380	270-320	36	High	10
6	320-450	320-410	320-370	45	High	8

Note to Table 1–57:

- (1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–58 lists the DLL frequency range specifications for Arria II GZ devices.

Table 1–58. DLL Frequency Range Specifications for Arria II GZ Devices

Frequency Mode	Frequency Range (MHz)		Available Phase Shift	DQS Delay Buffer Mode (1)	Number of Delay Chains
	-3	-4			
0	90-130	90-120	22.5°, 45°, 67.5°, 90°	Low	16
1	120-170	120-160	30°, 60°, 90°, 120°	Low	12
2	150-210	150-200	36°, 72°, 108°, 144°	Low	10
3	180-260	180-240	45°, 90°, 135°, 180°	Low	8
4	240-320	240-290	30°, 60°, 90°, 120°	High	12
5	290-380	290-360	36°, 72°, 108°, 144°	High	10
6	360-450	360-450	45°, 90°, 135°, 180°	High	8
7	470-630	470-590	60°, 120°, 180°, 240°	High	6

Note to Table 1–58:

- (1) Low indicates a 6-bit DQS delay setting; high indicates a 5-bit DQS delay setting.

Table 1–59 lists the DQS phase offset delay per stage for Arria II GX devices.

Table 1–59. DQS Phase Offset Delay Per Setting for Arria II GX Devices (Note 1), (2), (3)

Speed Grade	Min	Max	Unit
C4	7.0	13.0	ps
I3, C5, I5	7.0	15.0	ps
C6	8.5	18.0	ps

Notes to Table 1–59:

- (1) The valid settings for phase offset are -64 to +63 for frequency modes 0 to 3 and -32 to +31 for frequency modes 4 to 5.
(2) The typical value equals the average of the minimum and maximum values.
(3) The delay settings are linear.

IOE Programmable Delay

Table 1–66 lists the delay associated with each supported IOE programmable delay chain for Arria II GX devices.

Table 1–66. IOE Programmable Delay for Arria II GX Devices

Parameter	Available Settings (1)	Minimum Offset (2)	Maximum Offset								Unit	
			Fast Model			Slow Model						
			I3	C4	I5	I3	C4	C5	I5	C6		
Output enable pin delay	7	0	0.413	0.442	0.413	0.814	0.713	0.796	0.801	0.873	ns	
Delay from output register to output pin	7	0	0.339	0.362	0.339	0.671	0.585	0.654	0.661	0.722	ns	
Input delay from pin to internal cell	52	0	1.494	1.607	1.494	2.895	2.520	2.733	2.775	2.944	ns	
Input delay from pin to input register	52	0	1.493	1.607	1.493	2.896	2.503	2.732	2.774	2.944	ns	
DQS bus to input register delay	4	0	0.074	0.076	0.074	0.140	0.124	0.147	0.147	0.167	ns	

Notes to Table 1–66:

- (1) The available setting for every delay chain starts with zero and ends with the specified maximum number of settings.
- (2) The minimum offset represented in the table does not include intrinsic delay.

Table 1–67 lists the IOE programmable delay settings for Arria II GZ devices.

Table 1–67. IOE Programmable Delay for Arria II GZ Devices

Parameter	Available Settings (1)	Minimum Offset (2)	Maximum Offset						Unit	
			Fast Model		Slow Model					
			Industrial	Commercial	C3	I3	C4	I4		
D1	15	0	0.462	0.505	0.795	0.801	0.857	0.864	ns	
D2	7	0	0.234	0.232	0.372	0.371	0.407	0.405	ns	
D3	7	0	1.700	1.769	2.927	2.948	3.157	3.178	ns	
D4	15	0	0.508	0.554	0.882	0.889	0.952	0.959	ns	
D5	15	0	0.472	0.500	0.799	0.817	0.875	0.882	ns	
D6	6	0	0.186	0.195	0.319	0.321	0.345	0.347	ns	

Notes to Table 1–67:

- (1) You can set this value in the Quartus II software by selecting D1, D2, D3, D4, D5, and D6 in the Assignment Name column.
- (2) Minimum offset does not include the intrinsic delay.

Table 1–68. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G, H, I, J	J JTAG Timing Specifications	<p>High-speed I/O block: Deserialization factor (width of parallel data bus).</p> <p>JTAG Timing Specifications:</p> <p>The diagram illustrates the timing sequence for JTAG operations. It shows four signals: TMS, TDI, TCK, and TDO. TMS and TDI are high-speed parallel data buses. TCK is a clock signal. TDO is the output data. Various timing parameters are defined between these signals, such as t_{JCP}, t_{JCH}, t_{JCL}, t_{JPSU}, t_{JPH}, t_{JPZX}, t_{JPCO}, and t_{JPXZ}.</p>
K, L, M, N, O, P	PLL Specifications	<p>PLL Specification parameters:</p> <p>Diagram of PLL Specifications (1)</p> <p>The diagram shows a detailed block diagram of a PLL. It includes a Core Clock input, a Synchronizer, a Phase Frequency Detector (PFD), a Charge Pump (CP), a Loop Filter (LF), a Voltage Controlled Oscillator (VCO), a VCO post-scale counter K (with a value of 2), a Counter CO.C9, and various output paths for CLKOUT pins, GCLK, and RCLK. A feedback path from the output is labeled "External Feedback". A key legend indicates that blue boxes represent "Reconfigurable in User Mode".</p> <p>Notes:</p> <ul style="list-style-type: none"> (1) CoreClock can only be fed by dedicated clock input pins or PLL outputs. (2) This is the VCO post-scale counter K.
Q, R	R _L	Receiver differential input discrete resistor (external to the Arria II device).

Table 1–68. Glossary (Part 4 of 4)

Letter	Subject	Definitions
U, V	$V_{CM(DC)}$	DC common mode input voltage.
	V_{ICM}	Input common mode voltage: The common mode of the differential signal at the receiver.
	V_{ID}	Input differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage: Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage: Minimum DC input differential voltage required for switching.
	V_{IH}	Voltage input high: The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage.
	$V_{IH(DC)}$	High-level DC input voltage.
	V_{IL}	Voltage input low: The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage.
	$V_{IL(DC)}$	Low-level DC input voltage.
	V_{OCM}	Output common mode voltage: The common mode of the differential signal at the transmitter.
	V_{OD}	Output differential voltage swing: The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
W, X, Y, Z	W	High-speed I/O block: The clock boost factor.

Document Revision History

Table 1–69 lists the revision history for this chapter.

Table 1–69. Document Revision History (Part 1 of 2)

Date	Version	Changes
December 2013	4.4	Updated Table 1–34 and Table 1–35.
July 2012	4.3	<ul style="list-style-type: none"> ■ Updated the $V_{CCH_GXBL/R}$ operating conditions in Table 1–6. ■ Finalized Arria II GZ information in Table 1–20. ■ Added BLVDS specification in Table 1–32 and Table 1–33. ■ Updated input and output waveforms in Table 1–68.
December 2011	4.2	<ul style="list-style-type: none"> ■ Updated Table 1–32, Table 1–33, Table 1–34, Table 1–35, Table 1–40, Table 1–41, Table 1–54, and Table 1–67. ■ Minor text edits.
June 2011	4.1	<ul style="list-style-type: none"> ■ Added Table 1–60. ■ Updated Table 1–32, Table 1–33, Table 1–38, Table 1–41, and Table 1–61. ■ Updated the “Switching Characteristics” section introduction. ■ Minor text edits.

Table 1–69. Document Revision History (Part 2 of 2)

Date	Version	Changes
December 2010	4.0	<ul style="list-style-type: none"> ■ Added Arria II GZ information. ■ Added Table 1–61 with Arria II GX information. ■ Updated Table 1–1, Table 1–2, Table 1–5, Table 1–6, Table 1–7, Table 1–11, Table 1–35, Table 1–37, Table 1–40, Table 1–42, Table 1–44, Table 1–45, Table 1–57, Table 1–61, and Table 1–63. ■ Updated Figure 1–5. ■ Updated for the Quartus II version 10.0 release. ■ Updated the first paragraph for searchability. ■ Minor text edits.
July 2010	3.0	<ul style="list-style-type: none"> ■ Updated Table 1–1, Table 1–4, Table 1–16, Table 1–19, Table 1–21, Table 1–23, Table 1–25, Table 1–26, Table 1–30, and Table 1–35 ■ Added Table 1–27 and Table 1–29. ■ Added I3 speed grade information to Table 1–19, Table 1–21, Table 1–22, Table 1–24, Table 1–25, Table 1–30, Table 1–32, Table 1–33, Table 1–34, and Table 1–35. ■ Updated the “Operating Conditions” section. ■ Removed “Preliminary” from Table 1–19, Table 1–21, Table 1–22, Table 1–23, Table 1–24, Table 1–25, Table 1–26, Table 1–28, Table 1–30, Table 1–32, Table 1–33, Table 1–34, and Figure 1–4. ■ Minor text edits.
March 2010	2.3	<p>Updated for the Quartus II version 9.1 SP2 release:</p> <ul style="list-style-type: none"> ■ Updated Table 1–3, Table 1–7, Table 1–19, Table 1–21, Table 1–22, Table 1–24, Table 1–25 and Table 1–33. ■ Updated “Recommended Operating Conditions” section. ■ Minor text edits.
February 2010	2.2	Updated Table 1–19.
February 2010	2.1	<p>Updated for Arria II GX v9.1 SP1 release:</p> <ul style="list-style-type: none"> ■ Updated Table 1–19, Table 1–23, Table 1–28, Table 1–30, and Table 1–33. ■ Added Figure 1–5. ■ Minor text edits.
November 2009	2.0	<p>Updated for Arria II GX v9.1 release:</p> <ul style="list-style-type: none"> ■ Updated Table 1–1, Table 1–4, Table 1–13, Table 1–14, Table 1–19, Table 1–15, Table 1–22, Table 1–24, and Table 1–28. ■ Added Table 1–6 and Table 1–33. ■ Added “Bus Hold” on page 1–5. ■ Added “IOE Programmable Delay” section. ■ Minor text edit.
June 2009	1.2	<ul style="list-style-type: none"> ■ Updated Table 1–1, Table 1–3, Table 1–7, Table 1–8, Table 1–18, Table 1–23, Table 1–25, Table 1–26, Table 1–29, Table 1–30, Table 1–31, Table 1–32, and Table 1–33. ■ Added Table 1–32. ■ Updated Equation 1–1.
March 2009	1.1	Added “I/O Timing” section.
February 2009	1.0	Initial release.